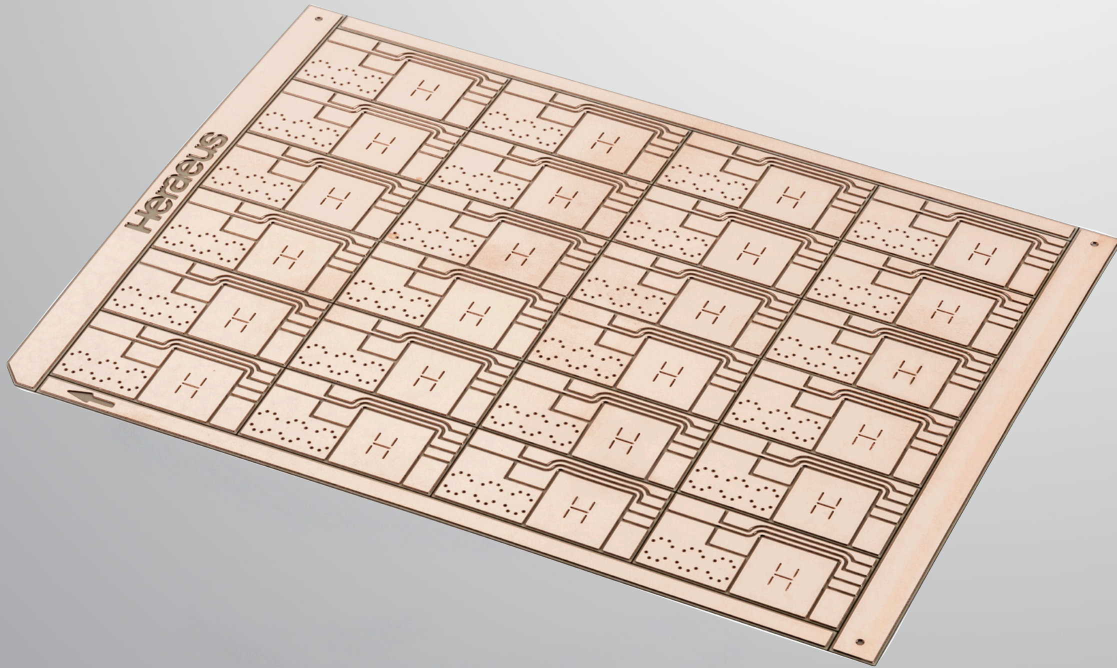
Heraeus

Electronics



Condura®.classic

Metal Ceramic Substrates Condura.extra DPS(1)

Alumina DCB facts

- Alumina ceramic Al_2O_3 (96 %)
  Thicknesses(2): 0.25 mm/Condura.extra0.32 mm/ 0.38mm/0.63 mm
- Direct Copper Bonding Cu-OFE
  Thicknesses(2): 0.2 mm/0.25 mm/0.3 mm/0.4 mm
- Single unit or master card size 7 " x 5 " (usable area)
- Surface finish: bare Cu, Ni, Ni/Au (others planned)

Key features

- Pre-qualified solutions & optimized surfaces
- Fast sample delivery target for standard material combinations
  Europe: 5 working days
  Worldwide: 15 working days (after drawing approval)
- Improved warpage / customization possible

Main properties raw Al_2O_3

	Rating	Unit
Thermal conductivity @ 20 °C	≥ 20	W/m.K
Bending strength	> 450	N/mm2
Young's modulus	≥ 300	GPa
Coefficient of thermal expansion (Al_2O_3) @ 100 °C - 600 °C	6.7 - 8.7	ppm/k

*Picture: substrate layout by courtesy of Fraunhofer IISB
(1) Development Product Information Sheet, preliminary values
(2) Different material combinations on request

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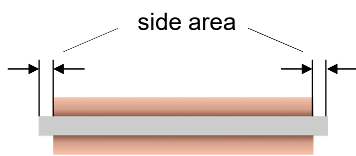
Design Rules Al2O3 DPIS[1]

Material properties raw Al_2O_3[3]

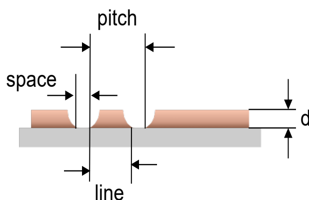
	Rating	Unit
Density	> 3.73	g/cm3
Electrical resistivity	≥ 1013	Ohm.cm
Dielectric strength	> 15	kV/mm

Copper free area



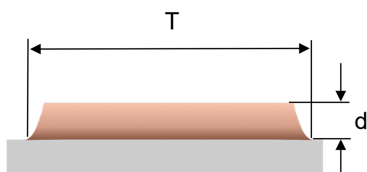
Thickness Cu [mm]	Min. side area [mm]
0.20	0.20
0.25	0.23
0.30	0.25
0.40	0.35

Structuring



Thickness Cu [mm]	Min. space [mm]	Min. line [mm]	Min. pitch [mm]
0.20	0.40	0.40	0.80
0.25	0.45	0.45	0.90
0.30	0.50	0.50	1.00
0.40	0.60	0.60	1.20

Etching tolerance



Tolerance length & width [mm]	Thickness Cu [mm]
Ttyp. = ± 0.15	d = 0.2
Ttyp. = ± 0.20	d ≤ 0.3
Ttyp. = ± 0.20	d ≤ 0.4

(1) Development Product Information Sheet, preliminary values
(3) Depends on supplier

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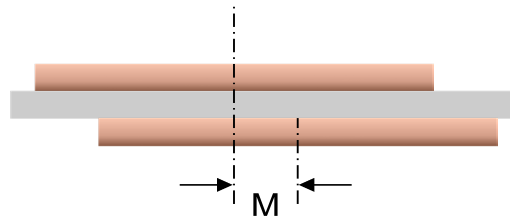
Design Rules Al_2O_3 DPIS[1]

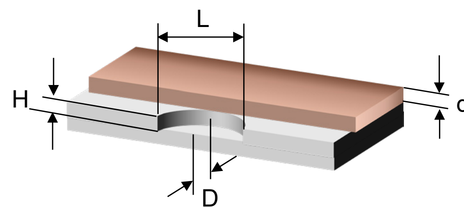
Tolerance and chip off

Tolerance



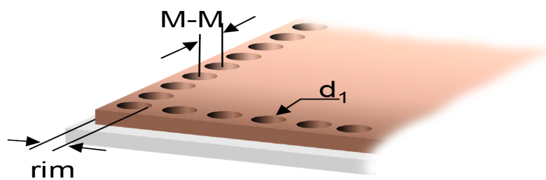
Mismatch M ≤ 0.1 mm
Tolerance of total thickness = + 7 % / -10 %

Chip-off at ceramic edge



Length L ≤ d
Depth D ≤ ½d
Height H ≤ ½d

Dimple structure



Thickness Cu [mm]	Dimple area rim [mm]	Dimple diamter d_1 [mm]	Dimple pitch M-M [mm]
0.20			
0.25	To be agreed		
0.30			
0.40			

Dimensions

General dimensions	Rating (mm)
Master card	138 x 190.5
Max. usable area	127 x 178
Minimum dimension for ceramic thickness ≤ 0.63 mm	10 x 10 (smaller on request)

Tolerances of single parts	Rating (mm)
Ceramic thickness ≤ 0.63 mm	+ 200 µm - 50 µm

Warpage behavior depends on specific layout, single part size and material combination and can only be specified after initial sample preparation.

Surface plating

Plating Method	Thickness (um)
Electroless Ni	3 - 7 (9% ± 2 % P)
Electroless NiAu	Ni 3 - 7 (9 % ± 2 % P) Au Class 1: 0.01 - 0.05 Au Class 2: 0.03 - 0.13

(1) Development Product Information Sheet, preliminary values

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Metal & hole properties

Roughness	
Rmax = 50 µm	
Ra ≤ 3.5 µm	Ra ≤ 1 µm
Rz ≤ 24 µm	Rz ≤ 16 µm

Different roughness by request

Minimum hole diameter	
d_{hole} = 1 mm	
Electrical conductivity raw copper	
$G_{Cu} = 58 \cdot 10^6$ S/m	
Thickness Cu	**Copper peeling strength**
0.30mm	> 4 N/mm

HET Academy
R&D Application Center

Besides offering Assembly Materials, Bonding Wires and Metal Ceramic Substrates, Heraeus Electronics provides matching material solutions and R&D oriented partnerships to create individual solutions.

Application conditions and assembly optimization

Thermal shock test cycles
-55 °C up to +150 °C
Under Investigation

Customized surface for assembly process

Optimization of surface and assembly process parameters available or in developement cooperation for:

- Sintering
- Solder wetting
- Heavy wire bondability

Heraeus Electronics offers:

- Reliable IATF 16949 certified supply of:
- Condura® + for example
- To be your competent one-stop materials solutions partner!

√ Condura®.prime AMB-Si_3N_4 (active metal brazed Si_3N_4)
√ Condura®.extra DCB-ZTA (zirconia-toughened alumina)
√ Condura®.classic DCB-Al2O3 (direct copper bonded Al_2O_3)
√ Engineering Services (Simulation, Prototype Design & Assembly Testing an Qualification, Material Analysis)
√ Pre-applied sinter / solder

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Document Number: 07.2024 I Version: 2022

(1) Development Product Information Sheet, preliminary values